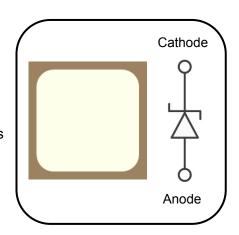


3rd Generation 1200V/30A SiC Schottky Barrier Diode

Features

- Revolutionary semiconductor material Silicon Carbide (SiC)
- No reverse recovery
- > High-speed switching performance
- > Temperature-independent switching behavior
- System cost / size savings due to reduced cooling requirements
- ▶ Junction temperature range from -55 $^{\circ}$ C to 175 $^{\circ}$ C
- RoHS compliant



Potential Applications

- Industrial power supplies: Industrial UPS
- Battery chargers
- Solar inverters
- Switch mode power supplies

Description



The SDS120J030B3 SiC Schottky Barrier Diode (SBD) has been developed using Sanan's advanced 3rd generation SiC SBD technology with the highest performance and reliability. It registers higher efficiency, higher operation temperature and lower loss and can be operated at higher frequency than Si-based solutions. As to the Schottky structure, it shows no recovery at turn-off and allows a low leakage current with reverse voltage up to 1200V. It can contribute to system miniaturization and achieve lightweight system design. Using RoHS compliant components, it is qualified for use in industrial application.

Product Specifications

Device	V _{RRM}	I _F (135℃)	V _F (25℃)	Qc
SDS120J030B3	1200V	45A	1.30V	175nC



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Table 1. Maximum Ratings

(Tc = 25℃, unless otherwise specified)

Parameter	Symbol	Value	Unit	Test conditions
Repetitive peak reverse voltage	V_{RRM}	1200		T _C = 25°C
Surge peak reverse voltage	V_{RSM}	1200	V	T _C = 25℃
DC reverse voltage	V _{DC}	1200		T _C = 25℃
		90		T _C = 25℃
Continuous forward current	I _F	45	А	T _C = 135℃
		30		T _C = 155℃
Surge non-repetitive forward current	I _{FSM}	290	Α	$T_C = 25^{\circ}C$, $t_p = 10$ ms, half sine pulse
Repetitive peak forward current	I _{FRM}	173	Α	$T_C = 25^{\circ}C$, $t_p = 10$ ms, half sine wave D = 0.1
i ² t value	∫i²dt	420	A ² s	$T_C = 25^{\circ}C$, $t_p = 10$ ms
Operating junction temperature	Tj	-55~175	$^{\circ}$	
Storage temperature	T _{stg}	-55~175	$^{\circ}$	

Table 2. Thermal Resistance

Davameter	C. mahal	,	/alues		Unit	Test
Parameter	Symbol	Min. Typ. N	Max.	condition		
Thermal resistance from junction to case	R _{th(j-c)}	1	0.38	1	°C/W	

^{*}Thermal Resistance is collected in TO247-2L

Table 3. Static Electrical Characteristics

(T_j = 25℃, unless otherwise specified)

Davamatav	Symbol	Values			11:4	Took oon diki oo
Parameter		Min.	Тур.	Max.	Unit	Test conditions
DC blocking voltage	V _{DC}	1200	1	1	V	Ι _R = 100 μΑ
Face and address	V _F	1	1.30	1.50	>	I _F = 30A, T _j = 25℃
Forward voltage		1	1.70	2.20		I _F = 30A, T _j = 175℃
Reverse current	I _R	1	3	72	μΑ	V _R = 1200V, T _j = 25°C
Reverse current		1	20	480		V _R = 1200V, T _j = 175℃

Datasheet

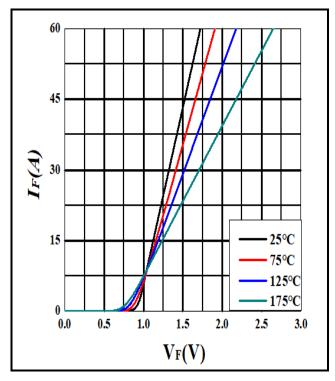
Table 4. Dynamic Electrical Characteristics

(T_j = 25℃, unless otherwise specified)

Danamatan.	Symbol	Values			11:4	Took oon diki oo
Parameter		Min.	Тур.	Max.	Unit	Test conditions
		1	2546	1		V _R = 0V, f = 1MHz
Total capacitance	С	1	160	1	pF	V _R = 400V, f = 1MHz
		1	117	1		V _R = 800V, f = 1MHz
Total capacitive charge	Qc	/	175	1	nC	V _R = 800V
Capacitance stored energy	Ec	1	50	1	μJ	V _R = 800V



Electrical Characteristic Diagrams



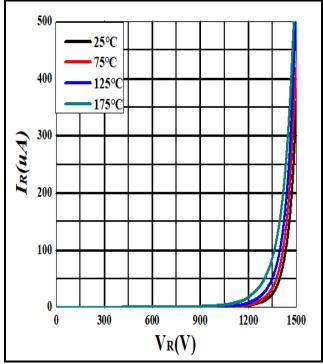
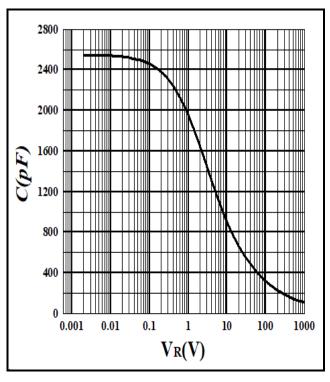
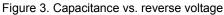


Figure 1. Forward characteristics

Figure 2. Reverse characteristics





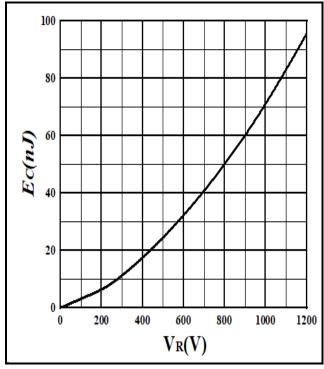


Figure 4. Capacitance stored energy



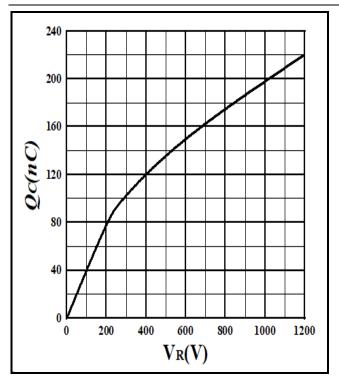


Figure 5. Total capacitance charge vs. reverse voltage

Ordering Information

Part Number	SDS120J030B3		
Package	Bare Die		
Packing Method	Wafer		
RoHS	Yes		



Important Notices - Read Carefully

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